

Press Release

July 9, 2019

3D Glass Solutions Successfully Closes Series B Round of Financing

ALBUQUERQUE, NEW MEXICO -- [3D Glass Solutions, Inc.](#) (3DGS), a leading innovator of glass-based, three-dimensional (3D) passive RF devices, announced today it has closed \$12 million in series B equity funding, bringing the company's total equity funding to more than \$19 million. Led by Nagase & Company, Ltd. (Nagase), a Japanese conglomerate specializing in next-generation chemistries and technologies across multiple market sectors, series B investment participants also include Sun Mountain Capital, Murata Manufacturing Co., Ltd. and [Lockheed Martin Ventures](#). With the successful close of this round of equity funding, 3DGS is now well-positioned for continued manufacturing expansion and acceleration of its technology roadmap.

"High-frequency devices capable of high-capacity, ultra-high-speed communication are essential for the practical application of next-generation 5G communication," notes Hideyuki Suzuki, Nagase Division Manager, Electro and Structural Products Division. "3DGS' novel glass material and proprietary processing technologies are key to the design, development and manufacture of high-frequency devices used in the industrial, aerospace and telecommunication sectors. Utilizing the 3DGS design and manufacturing platform, Nagase anticipates notable new business development opportunities."

3DGS provides unique design and manufacturing technology to produce glass-based RF passive and photonic devices with high-performance functionality necessary for next-generation, high-frequency wireless communication. 3DGS' patented glass-ceramic material, APEX® glass, enables the engineering and production of high-frequency 3D passive components which are integral to the efficiency of RF circuits and designs operating at very high frequency including 5G commercial and infrastructure systems, autonomous vehicle technology, high speed data, photonics, and military/aerospace.

"Building on the generous support from New Mexico's Economic Development Department and our series A investors, the closing of 3DGS' series B funding puts us on firm footing to achieve our ambitious growth objectives," says Mark Popovich, 3DGS President and CEO. "With an increasing order backlog and imminent move to a new





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20,000 sq. ft. manufacturing facility, 3DGS is well on the way to enabling broad GHz spectrum capability for multiple applications. We are expanding manufacturing operations, ramping to volume production and adding engineering resources for RF design and component manufacture. RF and microwave technology is ubiquitous and system designers are finding it more difficult than ever before to integrate more RF bands and increase functionality. 3DGS components solve system designers' need for high performance, small form factors and optimized component integration so that full performance potential and efficient, powerful connectivity in the GHz spectrum can be achieved."

For more information, visit www.3dglassolutions.com.

Forward-Looking Statements

Statements in this press release that are not strictly historical are forward-looking statements as defined in the Private Securities Litigation Reform Act of 1995. Forward-looking statements are based on management's current plans, estimates, and projections. 3D Glass Solutions undertakes no obligation to update any forward-looking statement in light of new information or future events. Actual results or outcomes may differ from those implied by the forward-looking statements as a result of a number of operational, technological, regulatory, and related risks and uncertainties.

About 3D Glass Solutions, Inc.

Based in Albuquerque, NM, 3D Glass Solutions, Inc. (3DGS) is an innovative RF passive device design and manufacturing company that develops novel, high-frequency 3D components. Leveraging the unique properties of its APEX® glass-ceramic material, the company's technology enables performance not possible with traditional 2D components. The result is passive components with superior electrical performance and ultra-low transmission loss at high frequencies ranging from 1 to 200 GHz. Using traditional semiconductor processes, 3DGS creates cost-effective, high-precision, high-volume scale components that meet the needs of both consumer commercial and mil/aero system designers. www.3dglassolutions.com

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